

Note: base parts are optional if the part is a only available from one manufacturer, e.g. a MCU, you may omit the base part

**Part: XY74HC00ASDF**

- base part: base Quad NAND DIP 14
- MPN: XY74HC00ASDF
- manufacturer: XY inc.

orderable part

**Part: AB74HC00ASDF**

- base part: base Quad NAND DIP 14
- MPN: AB 74HC00ASDF
- manufacturer: AB inc.

orderable part

**Part: base Quad NAND DIP 14**

- entity: Quad NAND
- package: DIP14
- pin-pad-mapping

**Package: QFN 16**

polygons for outline, texts and lines on silkscreen

- Pad** - name: 1
- Pad** - name: PAD

**Package: DIP 14**

polygons for outline, texts and lines on silkscreen

- Pad** - name: 1
- Pad** - name: 14

**Entity: Quad NAND**

- Gate** - name: A, - unit: s.e. NAND
- Gate** - name: D, - unit: s.e. NAND
- Gate** - name: P, - unit: Power

**Entity: Single NAND**

- Gate** - name: A, - unit: s.e. NAND
- Gate** - name: P, - unit: Power

**Padstack**

polygons...

**Padstack**

polygons...

**Padstack**

polygons...

**Symbol**

- unit: s.e. NAND
- lines...
- texts..
- pins..

**Unit: single-ended NAND**

- Pin** - primary name: A, - direction: input
- Pin** - primary name: B, - direction: input in
- Pin** - primary name: Y, - direction: output

**Unit: Power**

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Note: packages are supposed to only reference their own padstacks

